

In the Specificati n

At p. 1, before the "Technical Field" section, insert

--RELATED PATENT DATA

This patent resulted from a continuation application of U.S. Patent Application Serial No. 09/526,797, filed on April 22, 1997 which resulted from a file wrapper continuation application of Application Serial No. 08/597,196, filed February 6, 1996, now abandoned and entitled "Integrated Circuitry and a Semiconductor Processing Method of Forming a Series of Conductive Lines", naming Monte Manning as the inventor. This patent is also related to Application Serial No. 08/742,782, now U.S. Patent No. 6,096,636, issued August 1, 2000, which is a divisional application of Application Serial No. 08/597,196, now abandoned.--

Replace the paragraph beginning on page 6, lines 12-20 as follows:

Referring to Fig. 2, first insulating layer 18 and first conductive layer 16 ~~[[is]]~~ are photopatterned and etched through to substrate 14 to form a plurality of first conductive lines 19, 20, and 21 from first conductive layer 16 and provide a plurality of grooves 22 and 23 between first lines 19, 20, and 21. Accordingly in the preferred embodiment, first lines 19, 20, and 21 are capped by first insulating layer material 18. For purposes of continuing discussion, first lines 19, 20, and 21 have respective sidewalls 24. Also, grooves 22 and 23 have respective open widths 26, with 5000 Angstroms being an example.